

JLPI35B120RE2F7SN

LE2 PACK module with Gen.7 Trench/Fieldstop IGBT and Emitter Controlled diode and NTC



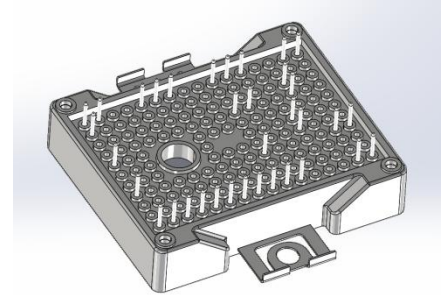
Features

• Electrical features

- $V_{CES} = 1200\text{ V}$
- $I_{C\text{ nom}} = 35\text{ A} / I_{CRM} = 70\text{ A}$
- Low V_{CESat}
- $10\mu\text{s}$ short circuit capability
- Overload operation up to 175°C

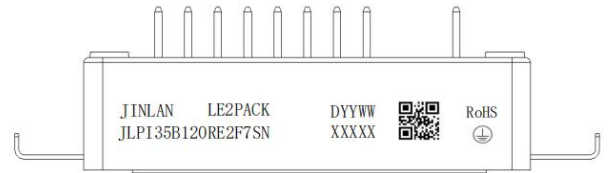
• Mechanical features

- Integrated NTC temperature sensor
- Isolated heatsink using DBC technology
- Low inductance case
- Solder contact technology



LE2 Pack

MARKING DIAGRAM



Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

JINLAN

JLPI35B120RE2F7SN

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QR code

= Company Name

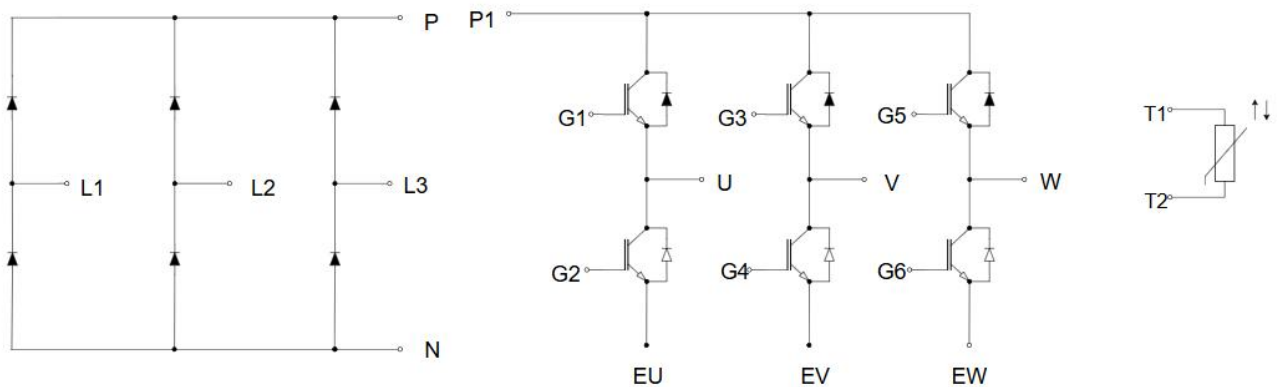
= Specific Device Code

= Year and Work Week Code

= Serial Number

= Custom Assembly

Description





Package Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, f=50Hz, t=60s	2.5	kV
Internal isolation		basic insulation(class 1, IEC 61140)	Al_2O_3	
Creepage distance	d_{creep}	terminal to heatsink	11.5	mm
Clearance	d_{clear}	terminal to heatsink	10	mm
Comparative tracking index (electrical)	CTI		>200	
RTI Elec.	RTI	housing	140	°C

Package Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Stray Inductance	LCE		--	30	--	nH
Module Lead Resistance, Terminal to Chip	$R_{AA'+CC'}$	$T_C=25^{\circ}C$, per switch	--	6.0	--	mΩ
Module Lead Resistance, Terminal to Chip	$R_{CC'+EE'}$	$T_C=25^{\circ}C$, per switch	--	5.0	--	mΩ
Storage Temperature Range	T_{STG}		-40		125	°C
Mounting Torque	M	M5, Screw	40		80	N.m
Weight	G		--	39	--	g

**IGBT, Inverter****Absolute Maximum Ratings** ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 30	V
I_C	Collector Current @ $T_C=25^\circ\text{C}$	70	A
	Collector Current @ $T_C=80^\circ\text{C}$	35	A
I_{CM}	Pulsed Collector Current, $t_p=1\text{S}$	105	A

Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition		Min	Typ	Max	Unit
V _{CE(sat)}	Collector–Emitter Saturation Voltage	I _C =35A, V _{GE} =15V	T _{vj} =25°C	--	1.70	2.50	V
			T _{vj} =175°C	--	1.90	--	
V _{GE(th)}	Gate Threshold Voltage	I _C =1mA, V _{CE} =V _{GE}		5.0	6.0	7.0	V
I _{CES}	Collector-Emitter Leakage Current	V _{GE} =0V, V _{CE} =1200V		--	--	10	uA
I _{GES}	Gate-Emitter Leakage Current	V _{GE} =30V, V _{CE} =0V		--	--	200	nA
R _{Gint}	Internal Gate Resistance	f=1MHz		--	0.6	--	Ω
C _{ies}	Input Capacitance	V _{CE} =25V, V _{GE} =0V, f=1MHz		--	4.20	--	nF
C _{oes}	Out Capacitance			--	0.107	--	nF
C _{res}	Reverse Transfer			--	0.024	--	nF
Q _G	Gate Charge	V _{CE} =960V, I _C =35A, V _{GE} =15V		--	0.147	--	uC
t _{d(on)}	Turn–On Delay Time	V _{CE} =600V, I _C =35A, V _{GE} =0/15V, R _{gon} =25Ω, R _{goff} =25Ω, Inductive Load T _j =25°C		--	71	--	ns
t _r	Rise Time			--	53	--	
t _{d(off)}	Turn–off Delay Time			--	261	--	
t _f	Fall Time			--	66.3	--	
E _{on}	Turn–On Switching Loss per Pulse			--	2.34	--	mJ
E _{off}	Turn Off Switching Loss per Pulse			--	1.44	--	
t _{d(on)}	Turn–On Delay Time	V _{CE} =600V, I _C =35A, V _{GE} =0/15V, R _{gon} =25Ω, R _{goff} =25Ω, Inductive Load T _j =175°C		--	TBD	--	ns
t _r	Rise Time			--	TBD	--	
t _{d(off)}	Turn–off Delay Time			--	TBD	--	
t _f	Fall Time			--	TBD	--	
E _{on}	Turn–on Switching Loss per Pulse			--	3.64	--	mJ
E _{off}	Turn Off Switching Loss per Pulse			--	2.00	--	
I _{sc}	SC Data	V _{GE} =15V, V _{CC} ≤600V, t _{sc} ≤10us, T _j ≤150°C		--	150	--	A
R _{thJC}	Thermal resistance	Junction-to-Case (per IGBT)		--	0.5	--	K/W
T _{vj op}		Temperature under switching conditions		-40		175 ¹⁾	°C

¹⁾ $T_{vj op} > 150^\circ\text{C}$ is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.



Diode, Inverter

Absolute Maximum Ratings (Tc = 25°C unless otherwise noted)

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	35	A
I_{FM}	Diode Maximum Forward Current $t_p=1ms$	105	A

Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Condition		Min	Typ	Max	Unit
V _F	Diode Forward Voltage	I _F =35A	T _J =25°C	--	1.70	2.50	V
			T _J =175°C	--	1.90	--	
Q _r	Recovered Charge	V _{CE} =600V,I _C =35A, V _{GE} =0/15V, R _{gon} =25Ω,R _{goff} =25Ω, Inductive Load T _J =25°C		--	1.01	--	μC
I _{RM}	Peak Reverse Recovery Current			--	37.7	--	A
T _{rr}	Reverse Recovery Time			--	120	--	ns
E _{rec}	Reverse Recovery Energy			--	0.42	--	mJ
Q _r	Recovered Charge	V _{CE} =600V,I _C =35A, V _{GE} =0/15V, R _{gon} =25Ω,R _{goff} =25Ω, Inductive Load T _J =175°C		--	TBD	--	μC
I _{RM}	Peak Reverse Recovery Current			--	TBD	--	A
T _{rr}	Reverse Recovery Time			--	TBD	--	ns
E _{rec}	Reverse Recovery Energy			--	TBD	--	mJ
R _{thJC}	Thermal resistance	Junction-to-Case (per diode)		--	0.72	--	K/W
T _{vj op}		Temperature under switching conditions		-40		175 ²⁾	°C

²⁾ $T_{vj\ op} > 150^{\circ}C$ is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

Diode, Rectifier

Absolute Maximum Ratings (Tc = 25°C unless otherwise noted)

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1600	V
I_F	Diode Continuous Forward Current	35	A
I_{FM}	Diode Maximum Forward Current $t_p=1ms$	70	A

Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V_F	Diode Forward Voltage	$I_F = 35\ A, T_J = 150\ ^{\circ}C$	--	0.95	--	V
I_R	Reverse Current	$T_J=175\ ^{\circ}C, V_R=1600V$	--	1.0	--	mA
R_{thJC}	Thermal resistance	Junction-to-Case (per diode)	--	0.53	--	K/W
$T_{vj\ op}$		Temperature under switching conditions	-40		175 ³⁾	$^{\circ}C$

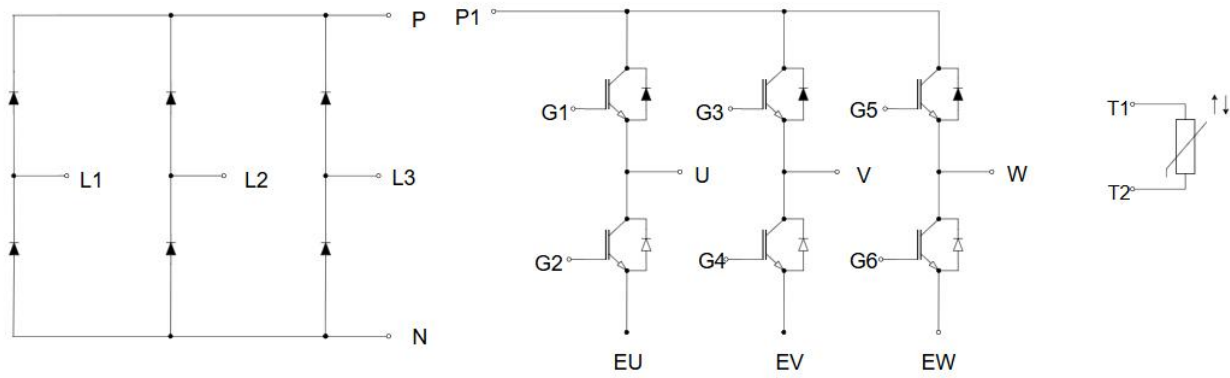
³⁾ $T_{vj\ op} > 150^{\circ}C$ is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

NTC Characteristics (Tc = 25°C unless otherwise noted)

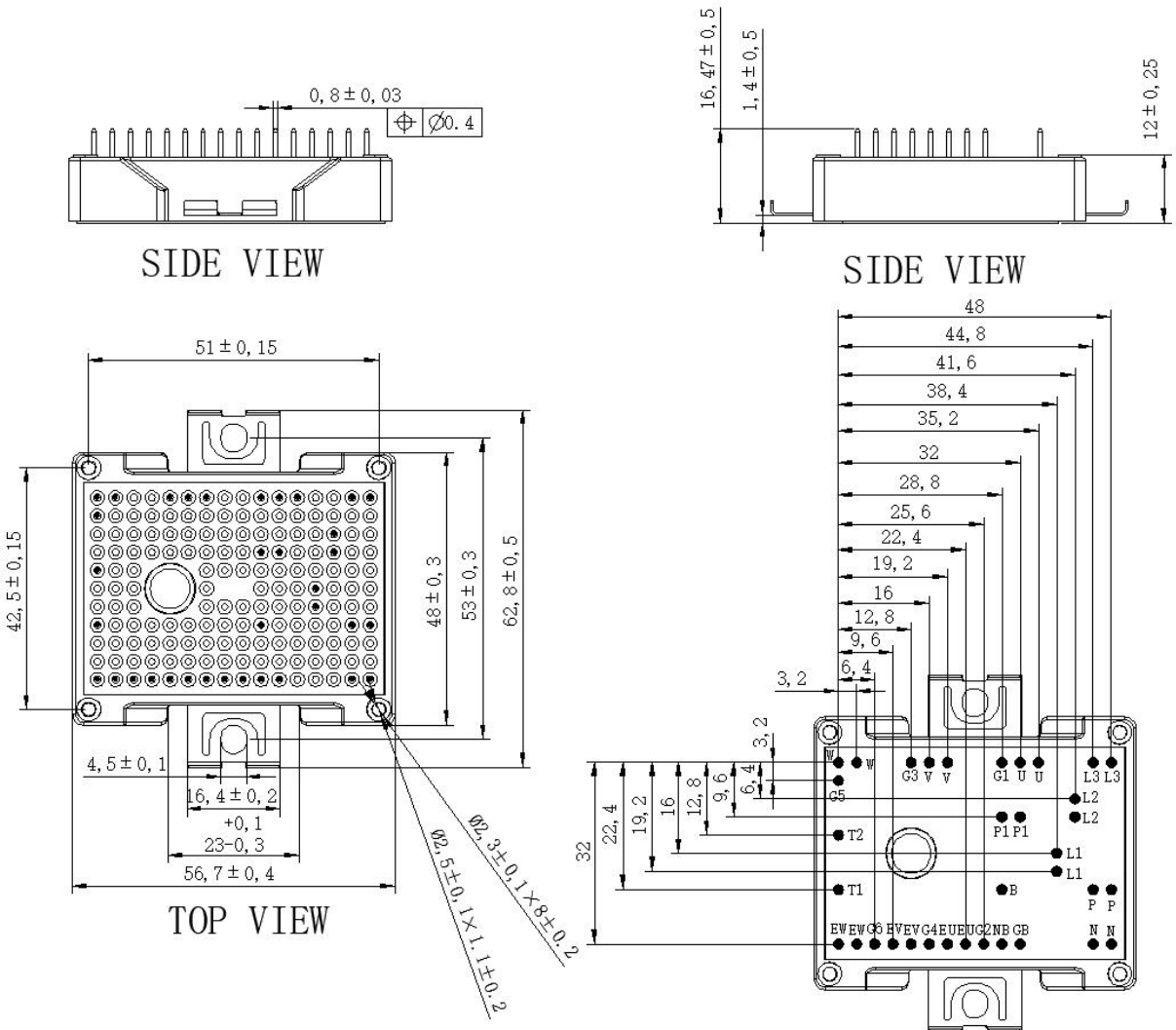
Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
R_{25}	Rated Resistance		--	5.0	--	k Ω
$\Delta R/R$	Deviation of R_{100}	$T_C=100\ ^{\circ}C, R_{100}=493.3\ \Omega$	-5	--	5	%
P_{25}	Power Dissipation		--	--	20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15K))]$	--	3375	--	K
$B_{25/80}$	B-value	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15K))]$	--	3411	--	K
$B_{25/100}$	B-value	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15K))]$	--	3433	--	K



CIRCUIT DIAGRAM



PACKAGE DIMENSION





REVISION HISTORY

Document version	Date of release	Description of changes
Rev.00	2025-06-06	Preview



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